8-bit Proprietary Microcontroller cmos

F²MC-8L MB89490 Series

MB89498/F499/PV490

■ DESCRIPTION

The MB89490 series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit single-chip microcontrollers.

In addition to a compact instruction set, the general-purpose, single-chip microcontroller contains a variety of peripheral functions such as 21-bit timebase timer, watch prescaler, PWM timer, 8/16-bit timer/counter, remote receiver circuit, LCD controller/driver, external interrupt 0 (edge), external interrupt 1 (level), 10-bit A/D converter, UART/SIO, SIO, I²C and watchdog timer reset.

The MB89490 series is designed suitable for compact disc/radio receiver controller as well as in a wide range of applications for consumer product.

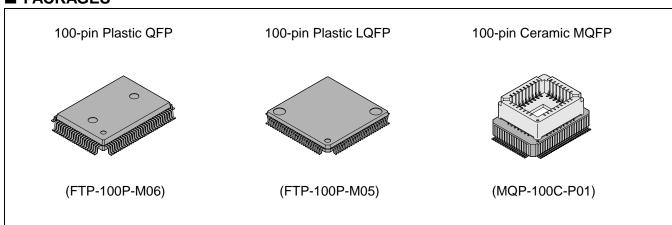
*: "F2MC", an abbreviation for FUJITSU Flexible Microcontroller, is a registered trademark of FUJITSU Ltd.

■ FEATURES

Package
 QFP, LQFP package for MB89F499, MB89498
 MQFP package for MB89PV490

(Continued)

■ PACKAGES





(Continued)

- High speed operating capability at low voltage
- Minimum execution time: 0.32 μs/12.5 MHz
- F2MC-8L family CPU core

Instruction set optimized for controllers

Multiplication and division instructions 16-bit arithmetic operations Branch instructions by test bit Bit manipulation instructions, etc.

- PLL circuit for sub-clock
 - Embedded for PLL clock multiplication circuit for sub-clock
 - Operating clock (PLL for sub-clock) can be selected from no multiplication or 4 times of the sub-clock oscillation frequency.
- 6 timers

PWM timer × 2

8/16-bit timer/counter × 2

21-bit timebase timer

Watch prescaler

External interrupt

Edge detection (selectable edge): 8 channels

Low level interrupt (wake-up function): 8 channels

• 10-bit A/D converter (8 channels)

10-bit successive approximation type

• UART/SIO

Synchronous/asynchronous data transfer capability

SIO

Switching of synchronous data transfer capability

• LCD controller/driver

Max 32 segments output × 4 commons

- I2C interface circuit
- Remote receiver circuit
- Low-power consumption mode

Stop mode (oscillation stops so as to minimize the current consumption.)

Sleep mode (CPU stops so as to reduce the current consumption to approx. 1/3 of normal.)

Watch mode (operation except the watch prescaler stops so as to reduce the power comsumption to an extremely low level.)

Sub-clock mode

- Watchdog timer reset
- I/O ports : Max 66 channels

■ PRODUCT LINEUP

Part number Parameter	MB89498	MB89F499	MB89PV490	
Classification	Mass production products (mask ROM product)	FLASH	Piggy-back (For evaluation or development)	
ROM size	48 K × 8-bit (internal ROM)	60 K × 8-bit (internal FLASH)	60 K × 8-bit (external ROM) *1	
RAM size	2 K × 8-bit	2 K × 8-bit	2 K × 8-bit	
CPU functions	Number of instructions Instruction bit length Instruction length Data bit length Minimum instruction execution time Minimum interrupt processing time	: 136 : 8-bit : 1 to 3 bytes : 1-bit, 8-bit, 16-bit : 0.32 µs/12.5 MHz : 2.88 µs/12.5 MHz		
Ports	General-purpose I/O ports (CMOS) : 56 pins Input ports (CMOS) : 2 pins N-channel open drain I/O ports : 8 pins Total : 66 pins			
21-bit timebase timer	Interrupt generation cycle (0.66 ms,	2.6 ms, 21.0 ms, 335.5 ms	s) at 12.5 MHz	
Watchdog timer	Reset generation cycle (167.8 ms to 335.5 ms) at 12.5 MHz			
PWM timer 0, 1	8-bit reload timer operation (supports square wave output and operating clock period : 1 tinst, 8 tinst, 16 tinst, 64 tinst) 8-bit accuracy PWM operation			
8/16-bit timer/counter 00, 01	Can be operated either as a 2-channel 8-bit timer/counter (timer 00 and timer 01, each with its own independent operating clock), or as one 16-bit timer/counter. In timer 00 or 16-bit timer/counter operation, event counter operation by external clock input and square wave output capability			
8/16-bit timer/counter 10, 11	Can be operated either as a 2-chang with its own independent operating of In timer 10-bit or 16-bit timer/counter input and square wave output capab	clock) , or as one 16-bit tim operation, event counter o	ner/counter.	
External interrupt 0 (edge)	8 independent channels (selectable	edge, interrupt vector, req	uest flag)	
External interrupt 1 (level)	8 channels (low level interrupt)			
A/D converter	10-bit accuracy × 8 channels A/D conversion function (conversion Supports repeated activation by inte			
LCD controller/driver	Common output Segment output LCD driving power (bias) pins LCD display RAM size	: 4 (Max) : 32 (Max) : 3 : 32 × 4 bits		

Part number Parameter	MB89498	MB89F499	MB89PV490		
UART/SIO	Synchronous/asynchronous of (Max baud rate : 97.656 Kbp (7-bit and 8-bit with parity bit		bit)		
SIO	8-bit serial I/O with LSB first/MSB first selectability 1 clock selectable from 4 operation clock (1 external shift clock and 3 internal shift clock : 0.64 μs, 2.56 μs, 10.24 μs at 12.5 MHz)				
I ² C* ²	1 channel (Use a 2-wire protocol to communicate with other device)				
Remote receiver circuit	Selectable maximum noise width removal Reversible input polarity				
Standby mode	Sleep mode, stop mode, watch mode and sub-clock mode				
Process	CMOS				
Operating voltage	2.2 V to 3.6 V	2.7 V to 3.6 V	2.7 V to 3.6 V		

^{*1:} Use MBM27C512 as the external ROM.

 $^{^{\}star}2$: $I^{2}C$ is complied to Philips $I^{2}C$ specification.

■ PACKAGE AND CORRESPONDING PRODUCTS

Part number Parameter	MB89498	MB89F499	MB89PV490
FPT-100P-M06	0	0	×
FPT-100P-M05	0	0	×
MQP-100C-P01	×	×	0

O : Availabe × : Not available

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the piggy-back product, verify its differences from the product that will be actually used. Take particular care on the following point: The stack area is set at the upper limit of the RAM.

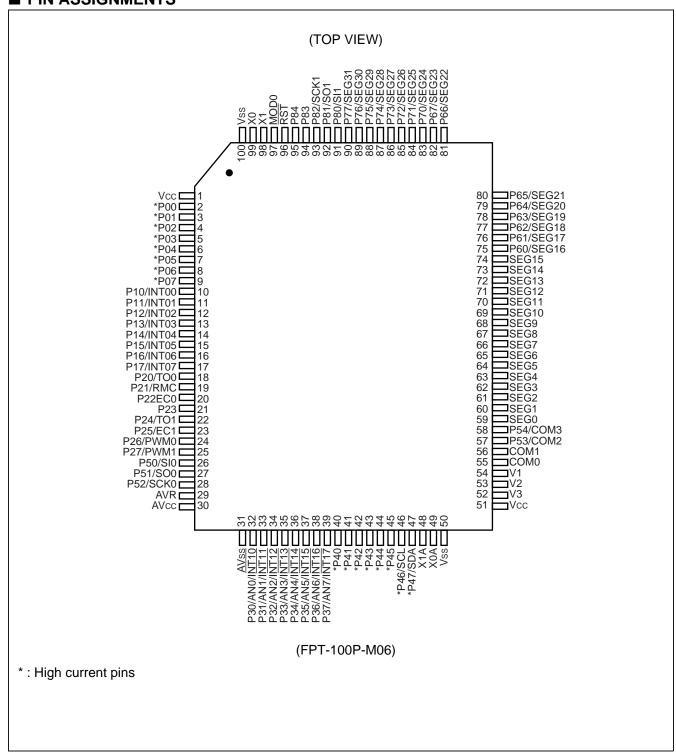
2. Current Consumption

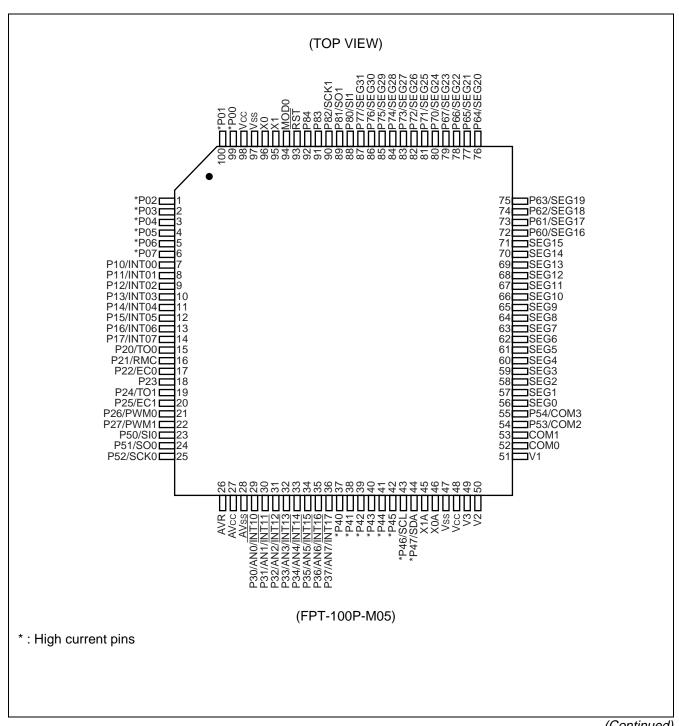
- For the MB89PV490, add the current consumed by the EPROM mounted in the piggy-back socket.
- When operating at low speed, the current consumed by the FLASH product is greater than that for the mask ROM product. However, the current consumption is roughly the same in sleep and stop mode.
- For more information, see "■ ELECTRICAL CHARACTERISTICS."

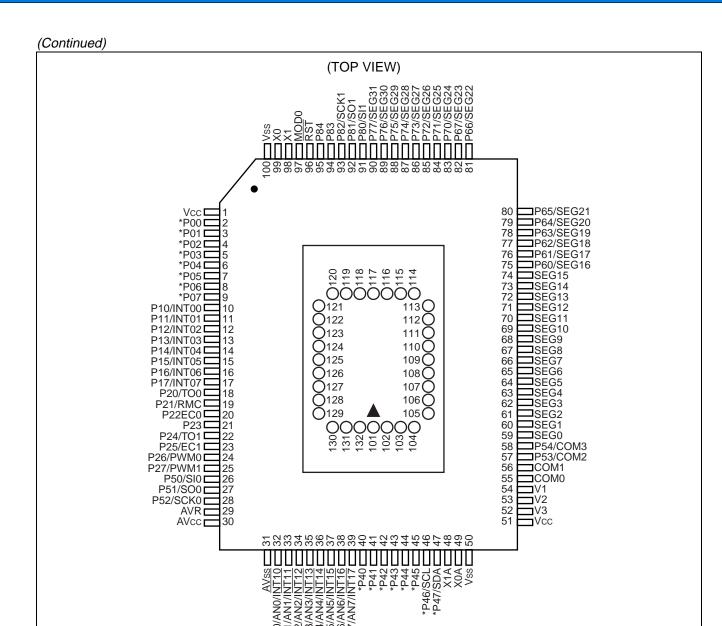
3. Oscillation Stabilization Wait Time after Power-on Reset

- For MB89PV490 and MB89F499, the power-on stabilization wait time cannot be selected after power-on reset.
- For MB89498, the power-on stabilization wait time can be selected after power-on reset.
- For more information, please refer to "■ MASK OPTIONS".

■ PIN ASSIGNMENTS







Pin assignment on package top (MB89PV490 only)

*: High current pins

Pin no.	Pin name								
101	N.C.	108	А3	115	O3	122	O8	129	A8
102	A15	109	A2	116	Vss	123	CE	130	A13
103	A12	110	A1	117	N.C.	124	A10	131	A14
104	A7	111	A0	118	O4	125	ŌĒ	132	Vcc
105	A6	112	N.C.	119	O5	126	N.C.		
106	A5	113	01	120	O6	127	A11		
107	A4	114	O2	121	07	128	A9		

(MQP-100C-P01)

N.C.: As connected internally, do not use.

■ PIN DESCRIPTION

Pin number			1/0 - ''			
MQFP*1/ QFP*2	LQFP*3	Pin name	I/O circuit type	Function		
99	96	X0		Connection pins for a crystal or other oscillator circuit.		
98	95	X1	А	An external clock can be connected to X0. In this case, leave X1 open.		
49	46	X0A		Connection pins for a crystal or other oscillator circuit.		
48	45	X1A	A	An external clock can be connected to X0A. In this case, leave X1A open.		
97	94	MOD0	В	Input pin for setting the memory access mode. Connect directly to Vss.		
95, 94	92, 91	P84, P83	J	General-purpose CMOS input port.		
96	93	RST	С	Reset I/O pin. The pin is an N-ch open-drain type with pull-up resistor and hysteresis input. The pin outputs an "L" level when an internal reset request is present. Inputting an "L" level initializes internal circuits.		
2 to 9	99 to 6	P00 to P07	D	General-purpose CMOS I/O port.		
10 to 17	7 to 14	P10/INT00 to P17/INT07	E	General-purpose CMOS I/O port. The pin is shared with external interrupt 0 input.		
18	15	P20/TO0	F General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 00 and 0			
19	16	P21/RMC	E	General-purpose CMOS I/O port. The pin is shared with remote receiver input.		
20	17	P22/EC0	E	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 00 and 01 input.		
21	18	P23	F	General-purpose CMOS I/O port.		
22	19	P24/TO1	F	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 10 and 11 output.		
23	20	P25/EC1	E	General-purpose CMOS I/O port. The pin is shared with 8/16-bit timer/counter 10 and 11 input.		
24	21	P26/PWM0	F	General-purpose CMOS I/O port. The pin is shared with PWM0 output.		
25	22	P27/PWM1	F	General-purpose CMOS I/O port. The pin is shared with PWM1 output.		
32 to 39	29 to 36	P30/AN0/INT10 to P37/AN7/INT17	G	General-purpose CMOS I/O port. The pin is shared with external interrupt 1 input and A/D converter input.		
40 to 45	37 to 42	P40 to P45	Н	General-purpose N-ch open-drain I/O port.		
46	43	P46/SCL	Н	General-purpose N-ch open-drain I/O port. The pin is shared with I ² C clock I/O.		

(Continued)

Pin number						
MQFP*1/ QFP*2	LQFP*3	Pin name	I/O circuit type	Function		
47	44	P47/SDA	Н	General-purpose N-ch open-drain I/O port. The pin is shared with I ² C data I/O.		
26	23	P50/SI0	E	General-purpose CMOS I/O port. The pin is shared with SIO data input.		
27	24	P51/SO0	F	General-purpose CMOS I/O port. The pin is shared with SIO data output.		
28	25	P52/SCK0	E	General-purpose CMOS I/O port. The pin is shared with SIO clock I/O.		
57	54	P53/COM2	F/I	General-purpose CMOS I/O port. The pin is shared with the LCD common output.		
58	55	P54/COM3	F/I	General-purpose CMOS I/O port. The pin is shared with the LCD common output.		
75 to 82	72 to 79	P60/SEG16 to P67/SEG23	F/I	General-purpose CMOS I/O port. The pin is shared with LCD segment output.		
83 to 90	80 to 87	P70/SEG24 to P77/SEG31	F/I	General-purpose CMOS I/O port. The pin is shared with LCD segment output.		
91	88	P80/SI1	E	General-purpose CMOS I/O port. The pin is shared with UART/SIO data input.		
92	89	P81/SO1	F	General-purpose CMOS I/O port. The pin is shared with UART/SIO data output.		
93	90	P82/SCK1	Е	General-purpose CMOS I/O port. The pin is shared with UART/SIO clock I/O.		
59 to 74	56 to 71	SEG0 to SEG15	I	LCD segment output-only pin.		
55, 56	52, 53	COM0, COM1	ı	LCD common output-only pin.		
54, 53, 52	51, 50, 49	V1 to V3	_	LCD driving power supply pin.		
1, 51	98, 48	Vcc	_	Power supply pin.		
50, 100	47, 97	Vss	_	Power supply pin (GND) .		
30	27	AVcc	_	A/D converter power supply pin.		
29	26	AVR	_	A/D converter reference voltage input pin.		
31	28	AVss	_	A/D converter power supply pin. Use at the same voltage level as Vss.		

*1: MQP-100C-P01

*2: FPT-100P-M06

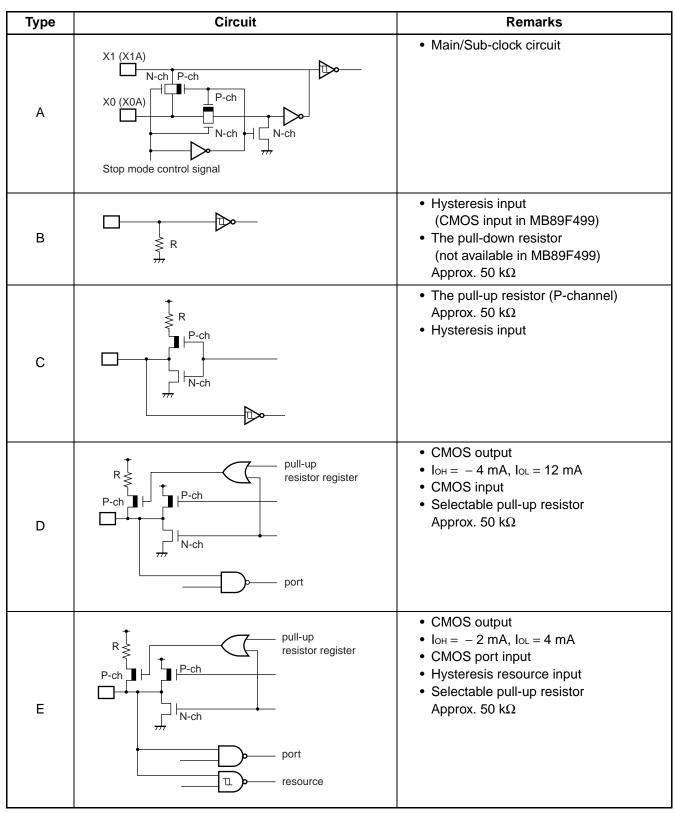
*3: FPT-100P-M05

• External EPROM Socket (MB89PV490 only)

Pin number	Din name	I/O	
MQFP*	Pin name	1/0	Function
102	A15		
131	A14		
130	A13		
103	A12		
127	A11		
124	A10		
128	A9		
129	A8	0	Address output pins.
104	A7	O	Address surpar pins.
105	A6		
106	A5		
107	A4		
108	A3		
109	A2		
110	A1		
111	A0		
122	08		
121	O7		
120	O6		
119	O5	1	Data input pins.
118	O4	•	
115	O3		
114	O2		
113	01		
101			
112	N.C.		Internally connected pins. Always leave open.
117	IN.C.	_	Internally confidence pills. Always leave open.
126			
116	Vss	0	Power supply pin (GND) .
123	CE	0	Chip enable pin for the EPROM. Outputs "H" in standby mode.
125	ŌĒ	0	Output enable pin for the EPROM. Always outputs "L".
132	Vcc	0	Power supply pin for the EPROM.

^{*:} MQP-100C-P01

■ I/O CIRCUIT TYPE



(Continued) Type	Circuit	Remarks
F	P-ch P-ch Port pull-up resistor register	 CMOS output IoH = -2 mA, IoL = 4 mA CMOS input Selectable pull-up resistor Approx. 50 kΩ
G	P-ch P-ch port resource analog	 CMOS output IoH = -2 mA, IoL = 4 mA CMOS port input VIH = 0.85 Vcc, VIL = 0.5 Vcc resource input Analog input Selectable pull-up resistor Approx. 50 kΩ
Н	N-ch port/resource	 N-ch open-drain output IoL = 15 mA CMOS port input CMOS resource input 5 V tolerance
I	P-ch N-ch P-ch N-ch	LCD segment output
J		CMOS input

■ HANDLING DEVICES

1. Preventing Latch-up

Latch-up may occur on CMOS IC if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- to high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in "■ ELECTRICAL CHARACTERISTICS" is applied between Vcc and Vss.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the maximum ratings.

Also, take care to prevent the analog power supply (AVcc and AVR) and analog input from exceeding the digital power supply (Vcc) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D

Connect to be AVcc = Vcc and AVss = AVR = Vss even if the A/D is not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Stabilization

Although $V_{\rm CC}$ power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. As stabilization guidelines, it is recommended to control voltage fluctuation so that $V_{\rm CC}$ ripple fluctuations (P-P value) will be less than 10% of the standard $V_{\rm CC}$ value at the commercial frequency (50 Hz to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset and wake-up from stop mode.

7. Treatment of Unused dedicated LCD pins

When dedicated LCD pins are not in use, keep them open.

■ PROGRAMMING AND ERASING FLASH MEMORY ON THE MB89F499

1. Flash Memory

The flash memory is located between 1000H and FFFFH in the CPU memory map and incorporates a flash memory interface circuit that allows read access and program access from the CPU to be performed in the same way as mask ROM. Programming and erasing flash memory is also performed via the flash memory interface circuit by executing instructions in the CPU. This enables the flash memory to be updated in place under the control of the internal CPU, providing an efficient method of updating program and data.

2. Flash Memory Features

- 60K bytes × 8-bit configuration (16 K + 8 K + 8 K + 28 K sectors)
- Automatic algorithm (Embedded algorithm*: Equivalent to MBM29LV200)
- Includes an erase pause and erase restart function
- Data polling and toggle bit for detection of program/erase completion
- Detection of program/erase completion via CPU interrupt
- Compatible with JEDEC-standard commands
- Sector Protection (sectors can be combined in any combination)
- No. of program/erase cycles: 10,000 (Min)

3. Procedure for Programming and Erasing Flash Memory

Programming and reading flash memory cannot be performed at the same time. Accordingly, to program or erase data to the flash memory, the program must first be copied from flash memory to RAM so that programming can be performed without program access from flash memory.

4. Flash Memory Register

• Flash memory control status register (FMCS)

Address	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Initial value
007Ан	INTE	RDYINT	WE	RDY	Reserved	Reserved	_	Reserved	000Х00-0в
	R/W	R/W	R/W	R	R/W	R/W	_	R/W	

^{*:} Embedded Algorithm is a trademark of Advanced Micro Devices.

5. Sector Configuration

The table below shows the sector configuration of flash memory and lists the addresses of each sector during CPU access and a flash memory programming.

· Sector configuration of flash memory

Flash Memory	CPU Address	Programmer Address*
16 K bytes	FFFFн to C000н	1FFFFн to 1С000н
8 K bytes	BFFFн to A000н	1BFFFн to 1A000н
8 K bytes	9FFFн to 8000н	19FFFн to 18000н
28 K bytes	7FFFн to 1000н	17FFFн to 11000н

^{* :} The programmer address is the address to be used instead of the CPU address when programming data from a parallel flash memory programmer. Use the programmer address on programming or erasing using a general-purpose programmer.

6. ROM Programmer Adaptor and Recommended ROM Programmers

Package	Applicable adapter model	Recommended writer
rackaye	Sunhayato Corp.	Ando Electric Co. Ltd.
FPT-100P-M06	FLASH-100QF-32DP-8LF2	AF9708 (ver 1.60 or later) *
FPT-100P-M05	FLASH-100SQF-32DP-8LF	AF9709 (ver 1.60 or later) *

^{*:} For the programmer and the version of the programmer, contact the Flash Support Group, Inc.

Inquirues: Sunhayato Corp.: TEL: : 81-(3)-3984-7791

FAX: 81-(3)-3971-0535

E-mail: adapter@sunhayato.co.jp

Flash Support Group, Inc.: FAX : 81-(53)-428-8377

E-mail: support@j-fsg.co.jp

■ PROGRAMMING TO THE EPROM WITH PIGGY-BACK/EVALUATION DEVICE

1. EPROM for Use

MBM27C512-20TV

2. Programming Socket Adapter

To program to the PROM using an EPROM programmer, use the socket adapter (manufacturer : Sunhayato Corp.) .

Package	Adapter socket part number
LCC-32 (Rectangle)	ROM-32LC-28DP-YG

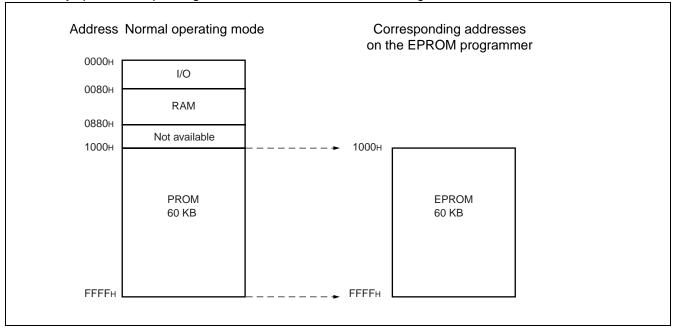
Inquiry: Sunhayato Corp.: TEL: 81-3-3984-7791

FAX: 81-3-3971-0535

E-mail: adapter@sunhayato.co.jp

3. Memory Space

Memory space corresponding to EPROM writer is shown in the diagram below.



4. Programming to the EPROM

- (1) Set the EPROM programmer to the MBM27C512.
- (2) Load program data into the EPROM programmer at 1000H to FFFFH.
- (3) Program to 1000H to FFFFH with the EPROM programmer.

■ ICE PROBE POD ADAPTOR OF PIGGY-BACK/EVA CHIP

The following conversion adapter is required to achieve the same pin layout as the FPT-100P-M05.

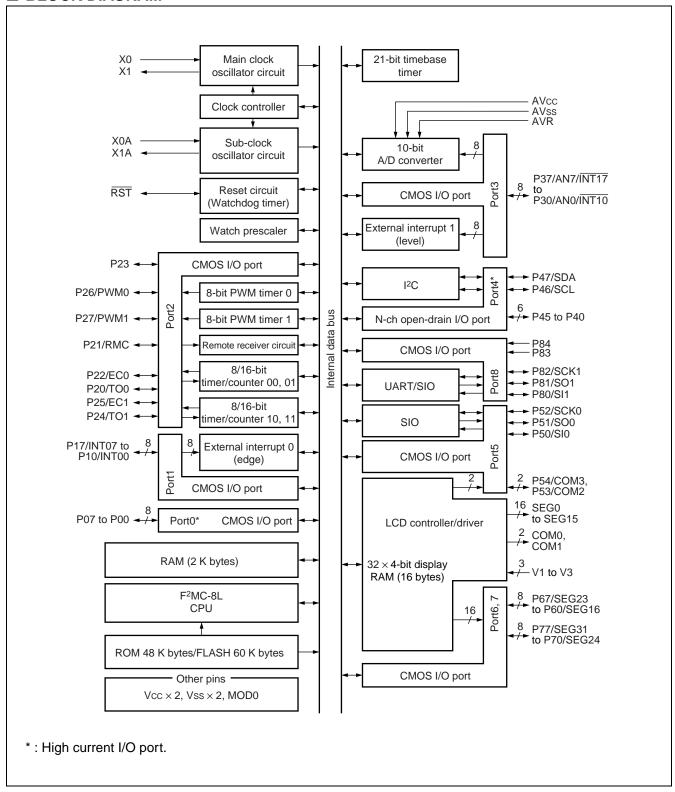
Adaptor part number: 100QF-100SQF-8L

Inquiry: Sunhayato Corp.: TEL: : 81-3-3984-7791

FAX: 81-3-3971-0535

E-mail: adapter@sunhayato.co.jp

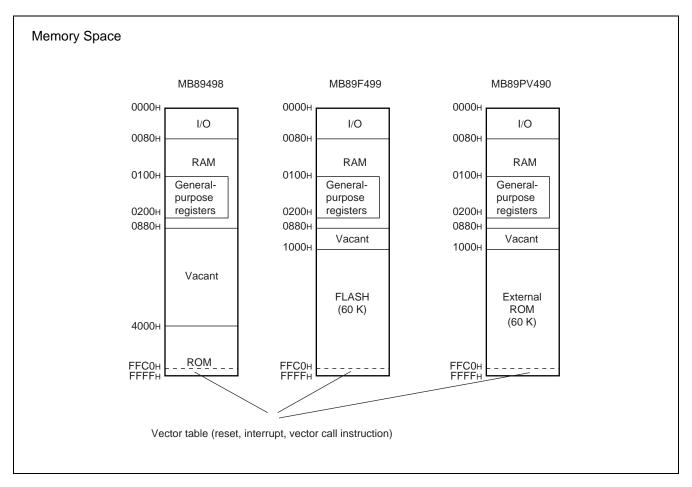
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

The microcontrollers of the MB89490 series offer a memory space of 64K bytes for storing all of I/O, data, and program areas. The I/O area is located the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt/reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89490 series is structured as illustrated below.



2. Registers

The F²MC-8L family has 2 types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following registers are provided:

Program counter (PC) : A 16-bit register for indicating instruction storage positions.

Accumulator (A) : A 16-bit temporary register for storing arithmetic operations, etc. When the

instruction is an 8-bit data processing instruction, the lower byte is used.

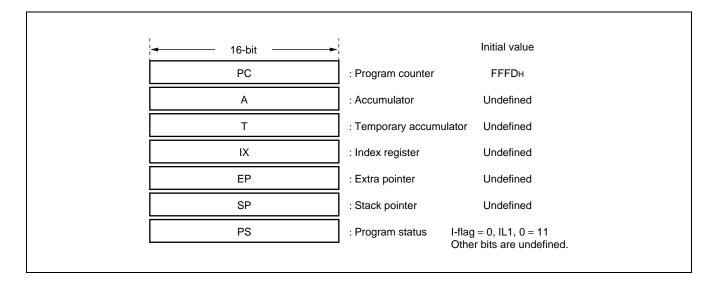
Temporary accumulator (T): A 16-bit register for performing arithmetic operations with the accumulator.

When the instruction is an 8-bit data processing instruction, the lower byte is used.

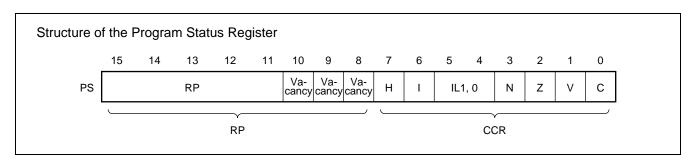
Index register (IX) : A 16-bit register for index modification.

Extra pointer (EP) : A 16-bit pointer for indicating a memory address. Stack pointer (SP) : A 16-bit register for indicating a stack area.

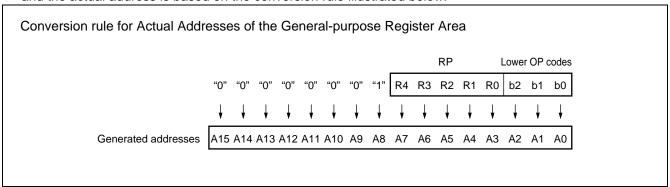
Program status (PS) : A 16-bit register for storing a register pointer and condition code.



The PS can further be divided into higher 8-bit for use as a register bank pointer (RP) and the lower 8-bit for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for controlling the CPU operations at the time of an interrupt.

H-flag: Set to "1" when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Clear to "0" otherwise. This flag is for decimal adjustment instructions.

I-flag: Interrupt is allowed when this flag is set to "1". Interrupt is prohibited when the flag is set to "0". Clear to "0" at reset.

IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	High-low
0	0	1	High
0	1	1	↑
1	0	2	↓
1	1	3	Low

N-flag: Set to "1" if the MSB is set to "1" as the result of an arithmetic operation. Clear to "0" otherwise.

Z-flag: Set to "1" when an arithmetic operation results in "0". Clear to "0" otherwise.

V-flag: Set to "1" if the complement on 2 overflows as a result of an arithmetic operation. Clear to "0" if the overflow does not occur.

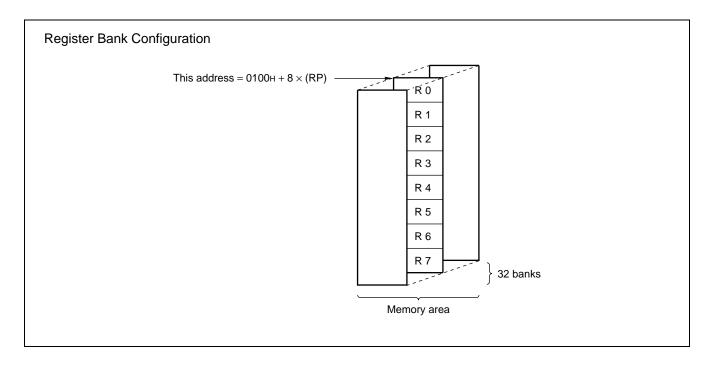
C-flag: Set to "1" when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Clear to "0" otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided:

General-purpose registers: An 8-bit register for storing data

The general-purpose registers are 8-bit and located in the register banks of the memory.

1 bank contains 8 registers. Up to a total of 32 banks can be used on the MB89490 series. The bank currently in use is indicated by the register bank pointer (RP) .



■ I/O MAP

Address	Register name	Register description	Read/Write	Initial value
00н	PDR0	Port 0 data register	R/W	XXXXXXXXB
01н	DDR0	Port 0 direction register	W*	0000000В
02н	PDR1	Port 1 data register	R/W	XXXXXXXXB
03н	DDR1	Port 1 direction register	W*	0000000В
04н	PDR2	Port 2 data register	R/W	0000000В
05н		(Reserved)		
06н	DDR2	Port 2 direction register	R/W	0000000в
07н	SYCC	System clock control register	R/W	Х-1ММ100в
08н	STBC	Standby control register	R/W	00010XXX _B
09н	WDTC	Watchdog timer control register	W*	0XXXX _B
0Ан	TBTC	Timebase timer control register	R/W	00000в
0Вн	WPCR	Watch prescaler control register	R/W	000000в
0Сн	PDR3	Port 3 data register	R/W	XXXXXXXX
0Дн	DDR3	Port 3 direction register	R/W	11111111в
0Ен	RSFR	Reset flag register	R	XXXX _B
0Fн	PDR4	Port 4 data register	R/W	11111111в
10н	PDR5	Port 5 data register	R/W	XXXXX _B
11н	DDR5	Port 5 direction register	R/W	00000в
12н	PDR6	Port 6 data register	R/W	XXXXXXXX
13н	DDR6	Port 6 direction register	R/W	0000000в
14н	PDR7	Port 7 data register	R/W	XXXXXXXXB
15н	DDR7	Port 7 direction register	R/W	0000000в
16н	PDR8	Port 8 data register	R/W	XXXXXB
17н	DDR8	Port 8 direction register	R/W	00000в
18н	EIC0	External interrupt 0 control register 0	R/W	0000000в
19н	EIC1	External interrupt 0 control register 1	R/W	0000000в
1Ан	EIC2	External interrupt 0 control register 2	R/W	0000000в
1Вн	EIC3	External interrupt 0 control register 3	R/W	0000000в
1Сн	EIE1	External interrupt 1 enable register	R/W	0000000в
1Dн	EIF1	External interrupt 1 flag register	R/W	Ов
1Ен	SMR	Serial mode register	R/W	0000000в
1F _H	SDR	Serial data register	R/W	XXXXXXXXB
20н	T01CR	Timer 01 control register	R/W	000000Х0в
21н	T00CR	Timer 00 control register	R/W	000000Х0в
22н	T01DR	Timer 01 data register	R/W	XXXXXXXXB

Address	Register name	Register description	Read/Write	Initial value
23н	T00DR	Timer 00 data register	R/W	XXXXXXXXB
24н	T11CR	Timer 11 control register	R/W	000000Х0в
25н	T10CR	Timer 10 control register	R/W	000000Х0в
26н	T11DR	Timer 11 data register	R/W	XXXXXXXXB
27н	T10DR	Timer 10 data register	R/W	XXXXXXXXB
28н	ADER	A/D input enable register	R/W	11111111в
29н	ADC0	A/D control register 0	R/W	-00000Х0в
2Ан	ADC1	A/D control register 1	R/W	-000001в
2Вн	ADDH	A/D data register (Upper byte)	R	XX _B
2Сн	ADDL	A/D data register (Lower byte)	R	XXXXXXXX
2Dн	CNTR0	PWM 0 timer control register	R/W	0-000000в
2Ен	COMR0	PWM 0 timer compare register	W*	XXXXXXXX
2Fн	SMC0	UART/SIO serial mode control register	R/W	0000000в
30н	SMC1	UART/SIO serial mode control register	R/W	0000000в
31н	SSD	UART/SIO serial status/data register	R/W	00001в
32н	SIDR/SODR	UART/SIO serial data register	R/W	XXXXXXXX
33н	SRC	UART/SIO serial rate control register	R/W	XXXXXXXX
34н	CNTR1	PWM 1 timer control register	R/W	0-000000в
35н	COMR1	PWM 1 timer compare register	W*	XXXXXXXX
36н	IBSR	I ² C bus status register	R	0000000в
37н	IBCR	I ² C bus control register	R/W	0000000В
38н	ICCR	I ² C clock control register	R/W	000XXXXXB
39н	IADR	I ² C address register	R/W	-XXXXXXXB
ЗАн	IDAR	I ² C data register	R/W	XXXXXXXX
3Вн	PLLCR	Sub PLL control register	R/W	0000в
3Сн to 3Fн		(Reserved)		
40н	RMN	Remote control counter register	R	XXXXXXXXB
41н	RMC	Remote control control register	R/W	0000000в
42н	RMS	Remote control status register	R/W	0Х000001в
43н	RMD	Remote control FIFO data register	R	XXXX _B
44н	RMCD0	Remote control compare register 0	R/W	11111111в
45н	RMCD1	Remote control compare register 1	R/W	11111111в
46н	RMCD2	Remote control compare register 2	R/W	11111111в
47н	RMCD3	Remote control compare register 3	R/W	11111111в
48н	RMCD4	Remote control compare register 4	R/W	11111111в

(Continued)

Address	Register name	Register description	Read/Write	Initial value
49н	RMCD5	Remote control compare register 5	R/W	11111111в
4Ан	RMCI	Remote interrupt register	R/W	0000-000в
4Вн to 5Dн		(Reserved)		
5Ен	LOCR	LCD controller output control register	R/W	-000000В
5 F н	LCR	LCD controller control register	R/W	00010000в
60н to 6Fн	VRAM	LCD data RAM	R/W	XXXXXXXXB
70н	PUCR0	Port 0 pull up resistor control register	R/W	11111111в
71н	PUCR1	Port 1 pull up resistor control register	R/W	11111111в
72н	PUCR2	Port 2 pull up resistor control register	R/W	11111111в
73н	PUCR3	Port 3 pull up resistor control register	R/W	11111111в
74н	PUCR5	Port 5 pull up resistor control register	R/W	11111в
75н	PUCR6	Port 6 pull up resistor control register	R/W	11111111в
76н	PUCR7	Port 7 pull up resistor control register	R/W	11111111в
77н	PUCR8	Port 8 pull up resistor control register	R/W	111в
78н to 79н		(Reserved)		
7Ан	FMCS	Flash memory control status registger	R/W	000Х00-0в
7Вн	ILR1	Interrupt level setting register 1	W*	11111111в
7Сн	ILR2	Interrupt level setting register 2	W*	11111111в
7Dн	ILR3	Interrupt level setting register 3	W*	11111111в
7 Ен	ILR4	Interrupt level setting register 4	W*	11111111в
7F н		(Reserved)	· '	

^{*:} Bit manipulation instruction cannot be used.

• Read/write access symbols

R/W: Readable and writable

R: Read-only W: Write-only

• Initial value symbols

0: The initial value of this bit is "0".1: The initial value of this bit is "1".

X: The initial value of this bit is undefined.

- : Unused bit.

M: The initial value of this bit is determined by mask option.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

Doromotor	Symbol	Rat	ing	Unit	Remarks		
Parameter	Symbol	Min	Max	Onit	Kemarks		
Power supply voltage*1	Vcc AVcc	Vss - 0.3	Vss + 4.0	V	AVcc must be equal to Vcc		
	AVR	Vss - 0.3	Vss + 4.0	V			
LCD power supply voltage	V1 to V3	Vss - 0.3	Vcc	V			
		Vss - 0.3	Vcc + 0.3	V	Except P40 to P47		
Input voltage *1	Vı	Vss - 0.3	Vss + 6.0	V	P40 to P47 in MB89PV490 and MB89498		
		Vss - 0.3	Vss + 5.5	V	P40 to P47 in MB89F499		
Output voltage*1	Vo	Vss - 0.3	Vcc + 0.3	V			
Maximum clamp current	I CLAMP	- 2.0	+ 2.0	mA	*2		
Total maximum clamp current	$\Sigma I_CLAMP $	_	20	mA	*2		
"L" level maximum output current	loL	_	15	mA			
"L" level average output current	IOLAV		4	mA	Average value (operating current × operating rate)		
"L" level total maximum output current	ΣΙοι		100	mA			
"L" level total average output current	Σ lolav	_	40	mA	Average value (operating current × operating rate)		
"H" level maximum output current	Іон	_	– 15	mA			
"H" level average output current	Іонач		- 4	mA	Average value (operating current × operating rate)		
"H" level total maximum output current	ΣІон		- 50	mA			
"H" level total average output current	ΣΙομαν	_	- 20	mA	Average value (operating current × operating rate)		
Power consumption	PD	_	300	mW			
Operating temperature	TA	- 40	+ 85	°C			
Storage temperature	Tstg	- 55	+ 150	°C			

^{*1 :} The parameter is based on $AV_{\text{SS}} = V_{\text{SS}} = 0.0 \text{ V}.$

^{*2: •} Applicable to pins: P00 to P07, P10 to P17, P20 to P27, P30 to P37, P50 to P52, P80 to P82

[•] Use within recommended operating conditions.

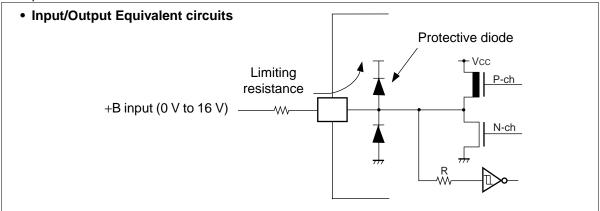
[•] Use at DC voltage (current) .

[•] The +B signal should always be applied with a limiting resistance placed between the +B signal and the microcontroller.

[•] The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.

(Continued)

- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the Vcc pin, and this may affect other devices.
- Note that if a +B signal is input when the microcontroller current is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
- Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the power-on result.
- Care must be taken not to leave the +B input pin open.
- Note that analog system input/output pins other than the A/D input pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signal input.
- Sample recommended circuits :



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

(AVss = Vss = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks		
raiailletei	Syllibol	Min	Max	5	iveniai və		
	Vcc AVcc	2.7*	3.6	٧	Normal operation assurance range	MB89PV490 and MB89F499	
Power supply voltage		2.2*	3.6	٧	Normal operation assurance range	MB89498	
		1.5	3.6	V	Retains the RAM state in stop mode		
	AVR	2.7	3.6	V			
LCD power supply voltage	V1 to V3	Vss	Vcc	V			
Operating temperature	Та	-40	+85	°C			

^{*:} These values depend on the operating conditions and the analog assurance range. See Figure 1, 2 and "5. A/D Converter Electrical Characteristics."

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

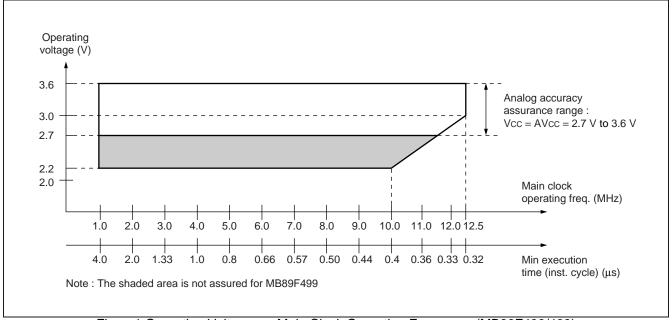


Figure 1 Operating Voltage vs. Main Clock Operating Frequency (MB89F499/498)

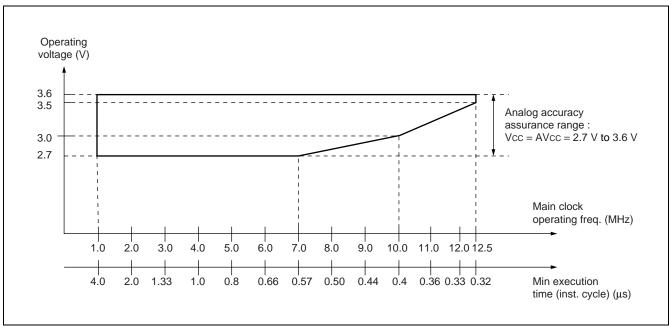


Figure 2 Operating Voltage vs. Main Clock Operating Frequency (MB89PV490)

Figure 1 and 2 indicate the operating frequency of the external oscillator at an instruction cycle of 4/Fch.

Since the operating voltage range is dependent on the instruction cycle, see figure 1 and 2 if the operating speed is switched using a gear.

3. DC Characteristics

(AVcc = Vcc = 3.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

D	01	D'a	O a sa l'it' a sa		Value		11	D
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"H" level	Vін	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P50 to P54, P60 to P67, P70 to P77, P80 to P84, SCL, SDA,		0.7 Vcc		Vcc + 0.3	V	
input voltage		D40 to D47	_	0.7 Vcc	_	Vss + 6.0	V	MB89498
		P40 to P47		0.7 Vcc	_	Vss + 5.5	V	MB89F499
Vins	Vihs	RST, MOD0, EC0, EC1, SCK0, SI0, SCK1, SI1, RMC, INT00 to INT07	_	0.8 Vcc	_	Vcc + 0.3	V	
	VIHA	INT10 to INT17	_	0.85 Vcc		Vcc + 0.3	V	
"L" level input voltage	VıL	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P54, P60 to P67, P70 to P77, P80 to P84, SCL, SDA,	_	Vss-0.3	_	0.3 Vcc	V	
Vıı	VILS	RST, MOD0, EC0, EC1, SCK0, SI0, SCK1, SI1, RMC, INT00 to INT07	_	Vss-0.3	_	0.2 Vcc	V	
	VILA	INT10 to INT17	_	Vss-0.3	_	0.5 Vcc	V	
Open-drain			_	Vss-0.3	_	Vss + 6.0	V	MB89498
output pin application voltage	VD	P40 to P47	_	Vss-0.3	—	Vss + 5.5	٧	MB89F499

(AVcc = Vcc = 3.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

Devemeter	Council of	Din	Condition		Value		11111111	Domonto
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"H" level output voltage	Vон	P10 to P17, P20 to P27, P30 to P37, P50 to P54, P60 to P67, P70 to P77, P80 to P82	lон = −2.0 mA	2.2	_	_	V	
		P00 to P07	Iон = -4.0 mA	2.2	_		V	
"L" level output voltage	Vol	P10 to P17, P20 to P27, P30 to P37, P50 to P54, P60 to P67, P70 to P77, P80 to P82, RST	IoL = 4.0 mA	_	_	0.4	V	
		P00 to P07	IoL = 12.0 mA	_	_	0.4	V	
		P40 to P47	IoL = 15.0 mA	_		0.4	V	
Input leakage current	lu	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P54, P60 to P67, P70 to P77, P80 to P84	0.45 V < Vı < Vcc	-5		+5	μА	Without pull-up resistor
Open-drain output leakage current	ILOD	P40 to P47	0.0 V < Vı < Vcc	-5	_	+5	μΑ	
Pull-down resistance	RDOWN	MOD0	Vı = Vcc	25	50	100	kΩ	Except MB89F499
Pull-up resistance	RPULL	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P50 to P54, P60 to P67, P70 to P77, P80 to P82, RST	V _I = 0.0 V	25	50	100	kΩ	When pull-up resistor is selected (except RST)
Common output impedance	Rvcом	COM0 to COM3	V1 to V3 = +3.0 V	_	_	2.5	kΩ	

(AVcc = Vcc = 3.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

D	01	D'	0 1111		Value		11	Damanla
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
Segment output impedance	Rvseg	SEG0 to SEG31	V1 to V3 = +3.0 V	_	_	15	kΩ	
LCD divided resistance	RLCD	_	Between Vcc and Vss	300	500	750	kΩ	
LCD controller/ driver leakage current	ILCDL	V1 to V3, COM0 to COM3, SEG0 to SEG31	_	-1		+1	μΑ	
			FcH = 12.5 MHz	_	8.0	12	mA	MB89F499
	Icc ₁		t _{inst} = 0.33 μs Main clock run mode		7.0	12.0	mA	MB89498
	Icc2		$\begin{aligned} F_{\text{CH}} &= 12.5 \text{ MHz} \\ t_{\text{inst}} &= 5.33 \mu\text{s} \\ \text{Main clock run mode} \end{aligned}$	_	1.0	3.0	mA	MB89F499 MB89498
	Iccs ₁		F _{CH} = 12.5 MHz t _{inst} = 0.33 μs Main clock sleep mode	_	3.0	5.0	mA	MB89F499 MB89498
	Iccs2		F _{CH} = 12.5 MHz t _{inst} = 5.33 μs Main clock sleep mode	_	0.6	2.0	mA	MB89F499 MB89498
Power supply current	Iccl	Vcc	F _{CL} = 32.768 kHz Sub-clock mode T _A = +25 °C	_	40.0	60.0	μΑ	MB89F499 MB89498
	ICCLPLL		$F_{CL} = 32.768 \text{ kHz}$ Sub-clock mode $T_A = +25 ^{\circ}\text{C}$ sub PLL \times 4	_	180.0	250.0	μΑ	MB89F499 MB89498
	Iccls		Fcl = 32.768 kHz Sub-clock sleep mode TA = +25 °C	_	14.0	30.0	μΑ	MB89F499 MB89498
	Ісст		Fcl = 32.768 kHz Watch mode Main clock stop mode TA = +25 °C	_	1.5	13.0	μА	MB89F499 MB89498

(Continued)

(AVcc = Vcc = 3.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

Parameter	Symbol	Pin	Condition		Value		Unit	Remarks
Farameter	Syllibol	FIII	Condition	Min	Тур	Max	Oilit	Remarks
	Іссн	Vcc	T _A = +25 °C Sub-clock stop mode	_	0.8	4.0	μА	MB89F499 MB89498
Power supply current	IA	AVcc	$AVcc = 3.0 \text{ V},$ $T_A = +25 \text{ °C}$	_	1.2	4.4	mA	A/D converting
	Іан		T _A = +25 °C	_	8.0	4.0	μΑ	A/D stop
Input capacitance	Cin	Except Vcc, Vss, AVcc, AVss, AVR	f = 1 MHz		10.0	_	pF	

4. AC Characteristics

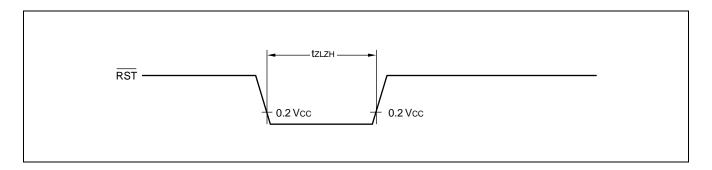
(1) Reset Timing

$$(AVcc = Vcc = 3.0 \text{ V}, AVss = Vss = 0.0 \text{ V}, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C)$$

Parameter	Symbol	Symbol Condition		ne	Unit	Remarks
Farameter	Symbol Condition -		Min	Max	Oilit	Remarks
RST "L" pulse width	t zlzh	_	48 theyl	_	ns	

Note: they is the oscillation cycle (1/Fch) to input to the X0 pin.

The MCU operation is not guaranteed when the "L" pulse width is shorter than tzlzh.



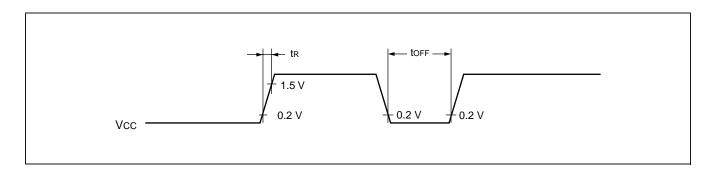
(2) Power-on Reset

$$(AV_{SS} = V_{SS} = 0.0 \text{ V}, T_A = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$$

Parameter	Symbol	Condition	Val	ue	Unit	Remarks	
rarameter	Syllibol	Condition	Min		Oilit	iveillai ks	
Power supply rising time	t R		_	50	ms		
Power supply cut-off time	t off		1		ms	Due to repeated operations	

Note: Make sure that power supply rises within the selected oscillation stabilization time.

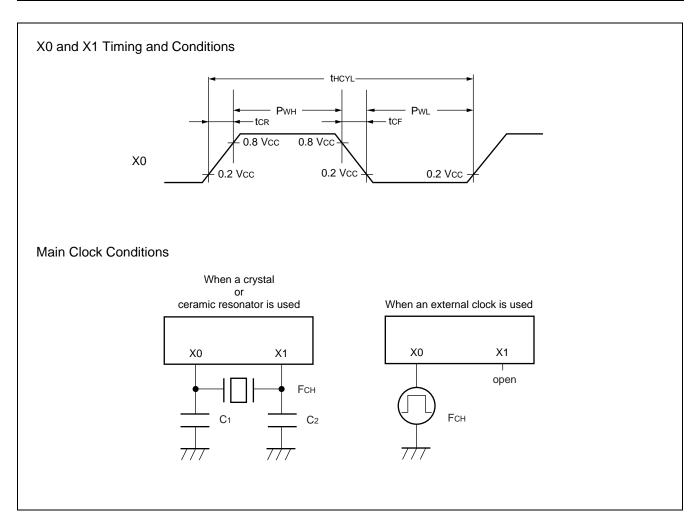
Rapid changes in power supply voltage may cause a power-on reset. If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.

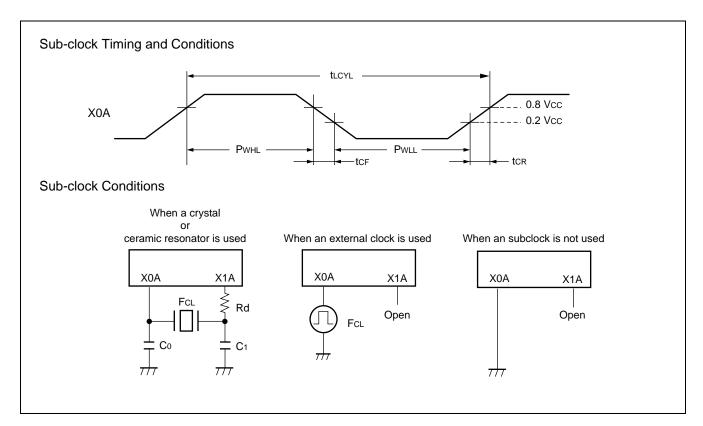


(3) Clock Timing

(AVss = Vss = 0.0 V,
$$T_A = -40$$
 °C to +85 °C)

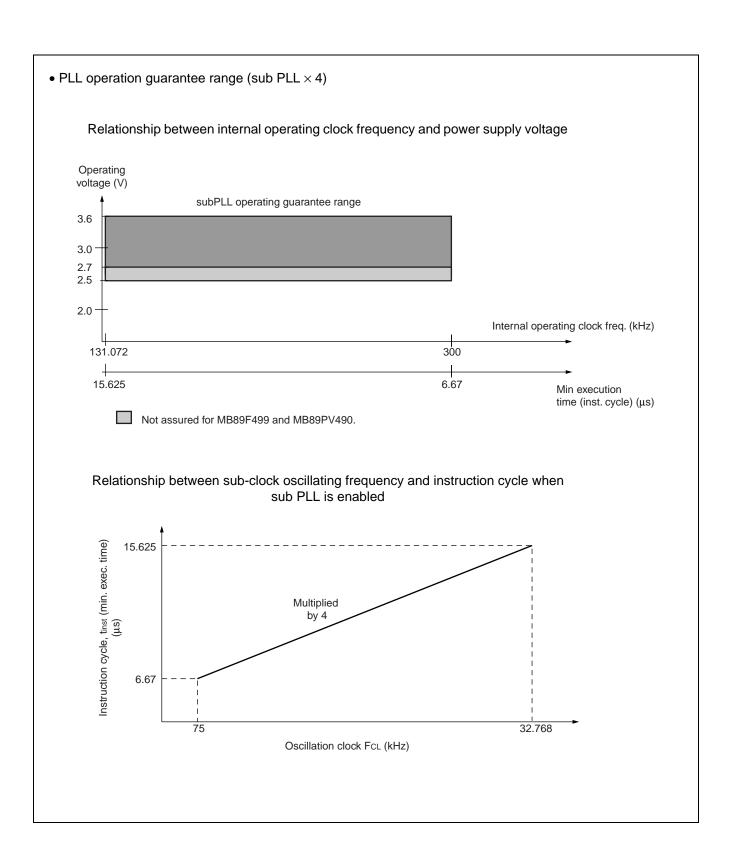
Doromotor	Symbol	Pin	Value			Unit	Remarks
Parameter			Min	Тур	Max	Unit	Remarks
Clock frequency	Fсн	X0, X1	1	_	12.5	MHz	
	FcL	X0A, X1A	_	32.768	75	kHz	
Clock cycle time	t HCYL	X0, X1	80	_	1000	ns	
	t LCYL	X0A, X1A	13.3	30.5	_	μs	
Input clock pulse width	Pwh PwL	X0	20	_		ns	
	P _{WHL} P _{WLL}	X0A		15.2		μs	External clock
Input clock rising/falling time	tcr tcr	X0, X0A		_	10	ns	





(4) Instruction Cycle

Parameter	Symbol	Value (typical)	Unit	Remarks		
Instruction cycle (minimum execution time)	t inst	4/Гсн, 8/Гсн, 16/Гсн, 64/Гсн	μs	(4/FcH) $t_{inst} = 0.32 \mu s$ when operating at FcH = 12.5 MHz		
		2/FcL, 1/2FcL	μs	(2/FcL) $t_{inst} = 61.036 \mu s$ when operating at FcL = 32.768 kHz		

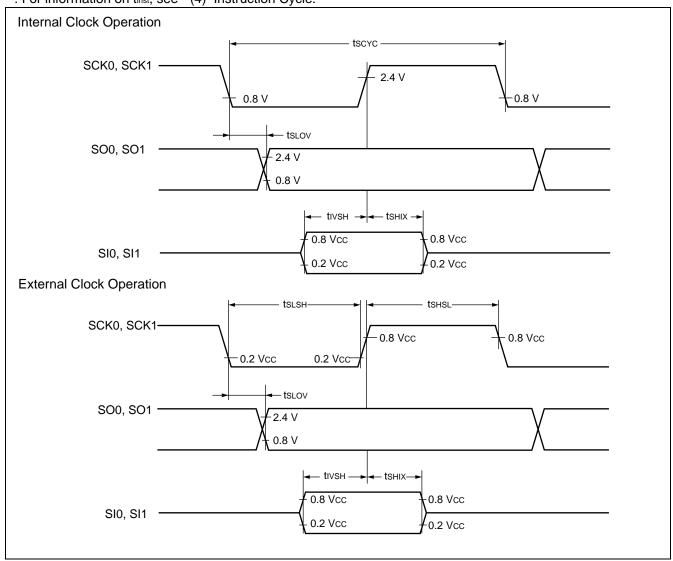


(5) Serial I/O Timing

(AVcc = Vcc = 3.0 V, AVss = Vss = 0.0 V, Ta = -40 °C to +85 °C)

Parameter	Symbol	Pin	Condition	Value		Unit	
Parameter	Symbol	PIII	Condition	Min	Max	Oill	
Serial clock cycle time	tscyc	SCK0, SCK1		2 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK0, SCK1, SO0, SO1	Internal shift clock	-200	200	ns	
Valid SI → SCK ↑	t ıvsh	SI0, SI1, SCK0, SCK1	mode	1/2 tinst*		μs	
$SCK \uparrow \rightarrow valid SI hold time$	tshix	SCK0, SCK1, SI0, SI1		1/2 tinst*	_	μs	
Serial clock "H" pulse width	t shsl	SCK0, SCK1	External shift clock mode	1 tinst*		μs	
Serial clock "L" pulse width	t slsh	JONO, JON		1 t inst*	_	μs	
$SCK \downarrow \to SO$ time	tsLov	SCK0, SCK1, SO0, SO1		0	200	ns	
Valid SI → SCK ↑	tivsh	SI0, SI1, SCK0, SCK1		1/2 tinst*	_	μs	
$SCK \uparrow \to valid \; SI \; hold \; time$	t shix	SCK0, SCK1, SI0, SI1		1/2 tinst*		μs	

*: For information on tinst, see "(4) Instruction Cycle."



(6) I²C Timing

 $(Vcc = 3.0V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

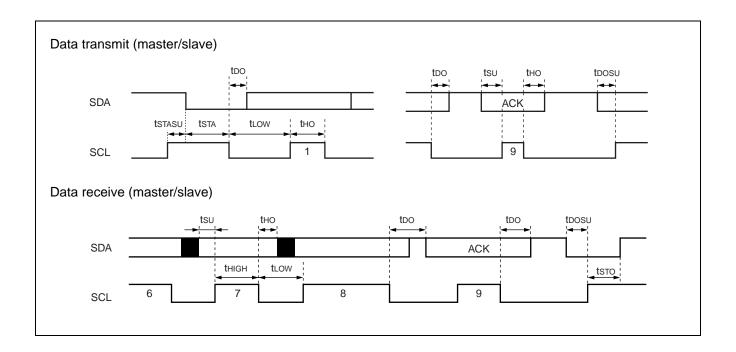
Parameter	Symbol	Pin	Value		Unit	Domorko	
Parameter	Symbol	Min Max		Max	Offic	Remarks	
Start condition output	t sta	SCL SDA	$\begin{array}{l} 1/4 \; t_{inst}^{\star 1} \times \\ M \times N - 20 \end{array}$	$\begin{array}{c} 1/4 \text{ tinst} \times \\ M \times N + 20 \end{array}$	ns	At master mode	
Stop condition output	tsто	SCL SDA	$\frac{1/4 \text{ tinst } \times}{(M \times N + 8) - 20}$	$1/4 \text{ tinst} \times (M^{*2} \times N^{*3} + 8) + 20$	ns	At master mode	
Start condition detect	t sta	SCL SDA	$1/4 t_{inst} \times 6 + 40$	_	ns		
Stop condition detect	tsто	SCL SDA	1/4 tinst × 6 + 40	_	ns		
Re-start condition output	t stasu	SCL SDA	$\begin{array}{c} 1/4 \text{ t}_{inst} \times \\ (M \times N + 8) \ -20 \end{array}$	$1/4 t_{inst} \times (M \times N + 8) + 20$	ns	At master mode	
Re-start condition detect	t stasu	SCL SDA	$1/4 t_{inst} \times 4 + 40$	_	ns		
SCL output LOW width	tLOW	SCL	$\begin{array}{l} 1/4 \ t_{\text{inst}} \times \\ M \times N - 20 \end{array}$	$\begin{array}{c} 1/4 \text{ t}_{\text{inst}} \times \\ M \times N + 20 \end{array}$	ns	At master mode	
SCL output HIGH width	tніgн	SCL	$\begin{array}{c} 1/4 \text{ t}_{inst} \times \\ (M \times N + 8) \ -20 \end{array}$	$1/4 t_{inst} \times (M \times N + 8) + 20$	ns	At master mode	
SDA output delay	t DO	SDA	$1/4~t_{\text{inst}}\times 4-20$	$1/4 t_{inst} \times 4 + 20$	ns		
SDA output setup time after interrupt	toosu	SDA	$1/4 t_{inst} \times 4 - 20$	_	ns	*4	
SCL input LOW pulse width	tLOW	SCL	$1/4 t_{inst} \times 6 + 40$	_	ns		
SCL input HIGH pulse width	t HIGH	SCL	$1/4 t_{inst} \times 2 + 40$	_	ns		
SDA input setup time	t su	SDA	40	_	ns		
SDA hold time	tно	SDA	0	_	ns		

^{*1:} For information in tinst, see " (4) Instruction Cycle".

^{*2:} M is defined in the I²C clock control register ICCR bit 4 and bit 3 (CS4 and CS3). For details, please refer to the H/W manual register explanation.

^{*3:} N is defined in the I²C clock control register ICCR bit 2 to bit 0 (CS2 to CS0).

^{*4:} When the interrupt period is greater than SCL "L" width, SDA and SCL output (Standard) value is based on hypothesis when rising time is 0 ns.

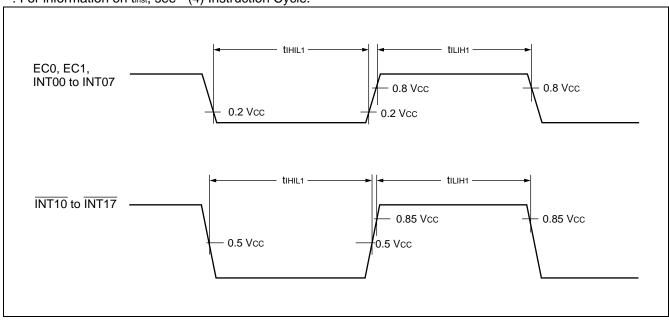


(7) Peripheral Input Timing

(AVcc = Vcc = 3.0 V, AVss = Vss = 0.0 V, $T_A = -40$ °C to +85 °C)

Parameter	Symbol	Pin	Value		Unit	Remarks
Farameter	Symbol	FIII	Min	Max	Oilit	iveillai və
Peripheral input "H" pulse width 1	tılıH1	EC0, EC1, INT00 to	2 tinst*	_	μs	
Peripheral input "L" pulse width 1	t _{IHIL1}	INT07, INT10 to INT17	2 tinst*	_	μs	

*: For information on tinst, see " (4) Instruction Cycle."



5. A/D Converter Electrical Characteristics

(1) A/D Converter Electrical Characteristics

(AVcc = Vcc = 2.7 V to 3.6 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

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Parameter	Symbol	Pin	Value			Unit	Remarks
i arameter			Min	Тур	Max	Oiiit	Remarks
Resolution			_	10	_	bit	
Total error			_	_	±3.0	LSB	
Linearity error	_		_	_	±2.5	LSB	
Differential linearity error			_	_	±1.9	LSB	
Zero transition voltage	Vот	_	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	mV	
Full-scale transition voltage	V _{FST}		AVcc – 3.5 LSB	AVcc – 1.5 LSB	AVcc – 0.5 LSB	mV	
A/D mode conversion time	_		30 tinst*	_		μs	
Analog port input current	lain	AN0 to	_	_	10	μΑ	
Analog input voltage	Vain	AN7	AVss	_	AVR	V	
Reference voltage	_		AVss + 2.7	_	AVcc	V	
Reference voltage supply	lR	AVR	_	95.0	170.0	μΑ	A/D is activated
current	Іпн		_	_	4.0	μΑ	A/D is stopped

^{*:} For information on t_{inst}, see " (4) Instruction Cycle" in "4. AC Characteristics".

(2) A/D Converter Glossary

Resolution

Analog changes that are identifiable with the A/D converter.

When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

• Linearity error (unit : LSB)

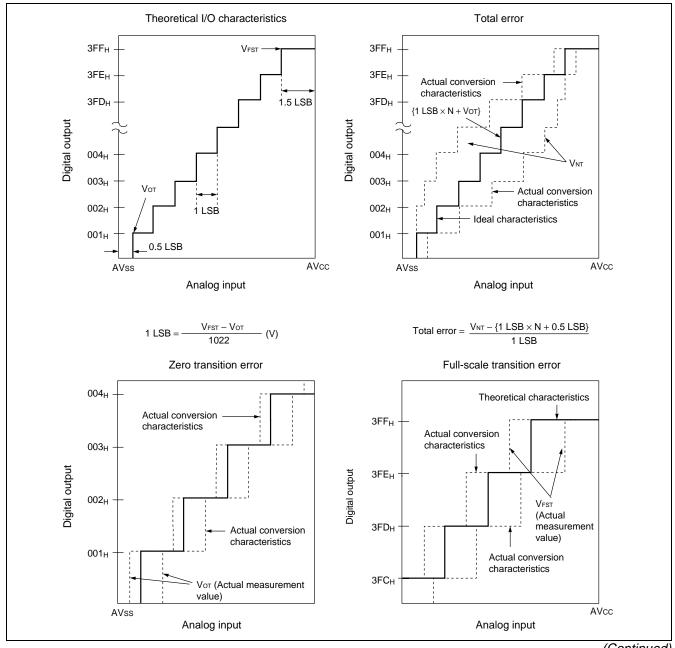
The deviation of the straight line connecting the zero transition point ("00 0000 0000" \leftrightarrow "00 0000 0001") with the full-scale transition point ("11 1111 1111" \leftrightarrow "11 1111 1110") from actual conversion characteristics.

• Differential linearity error (unit : LSB)

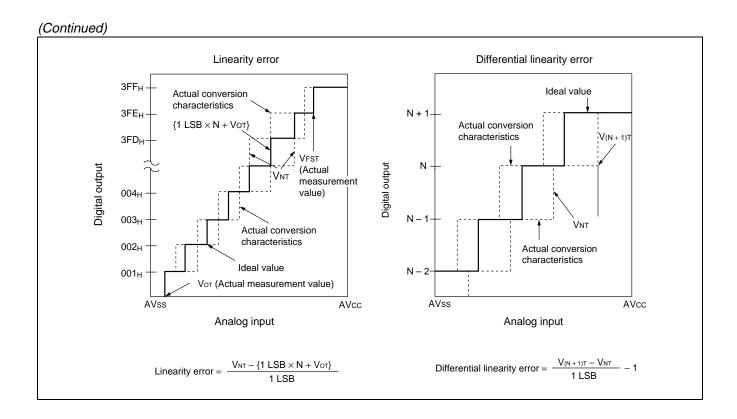
The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value.

• Total error (unit : LSB)

The difference between theoretical and actual conversion values.

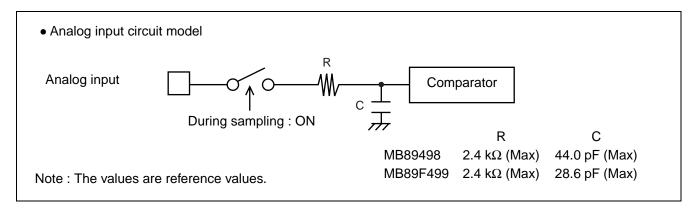


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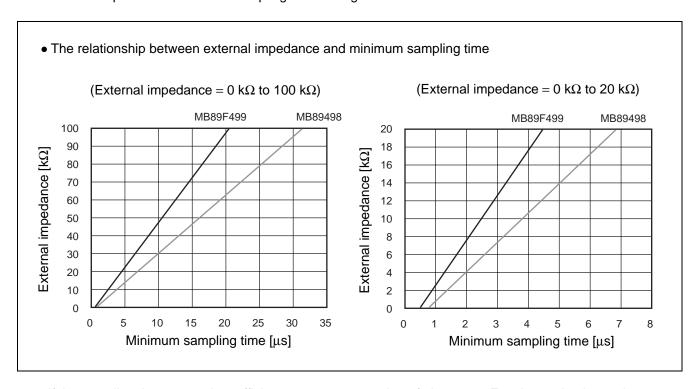


(3) Notes on Using A/D Converter

- About the external impedance of the analog input and its sampling time
 - A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting A/D conversion precision.



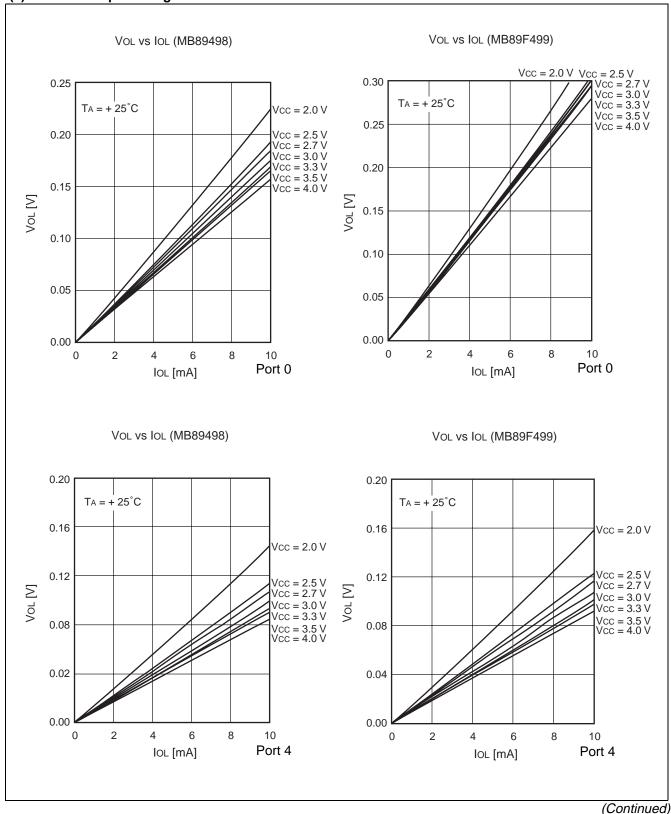
• To satisfy the A/D conversion precision standard, consider the relationship between the external impedance and minimum sampling time and either adjust the resistor value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value.

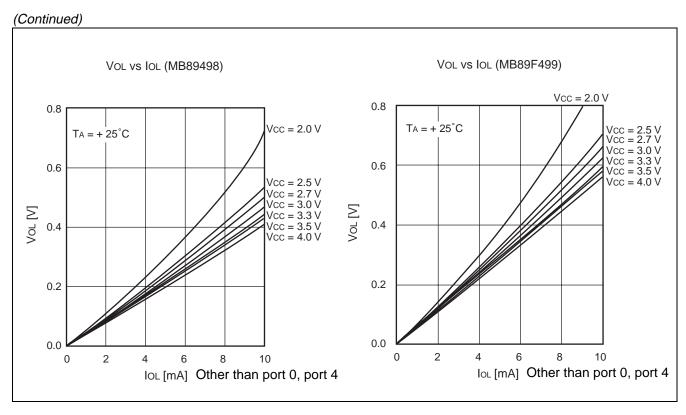


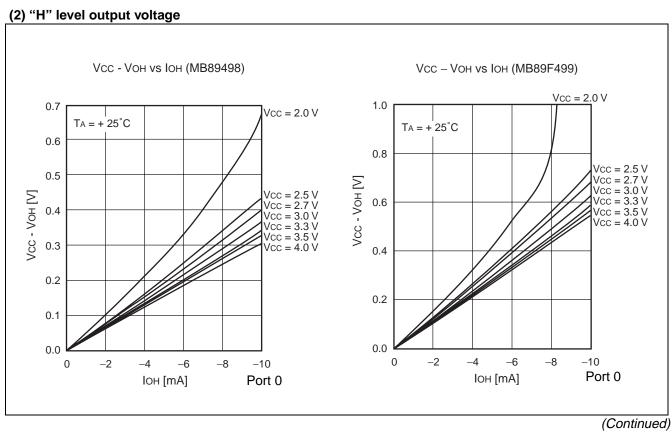
- If the sampling time cannot be sufficient, connect a capacitor of about 0.1 μF to the analog input pin.
- About errors
 As |AVRH AVss| becomes smaller, values of relative errors grow larger.

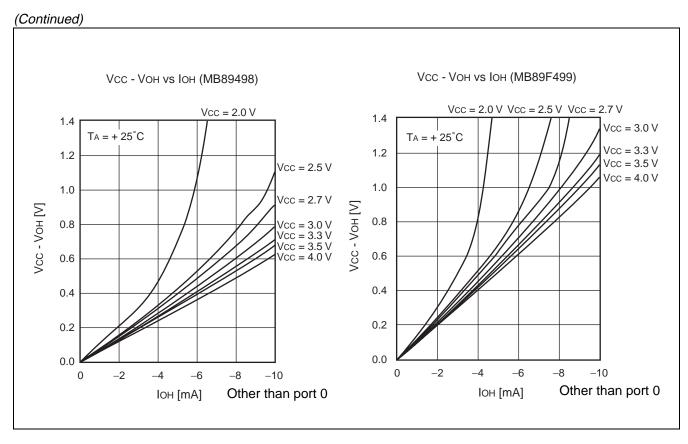
■ EXAMPLE CHARACTERISTICS

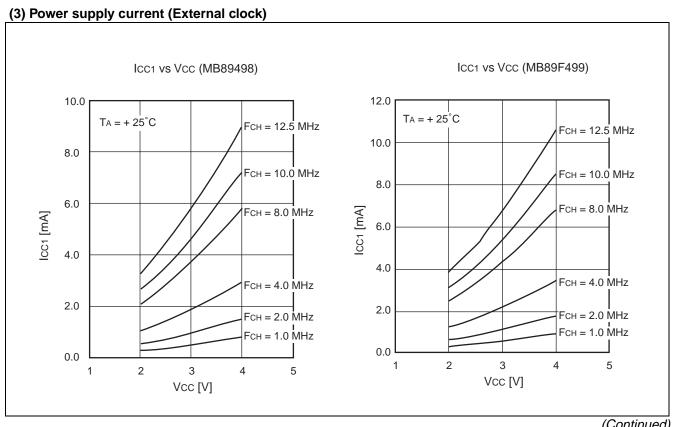
(1) "L" level output voltage

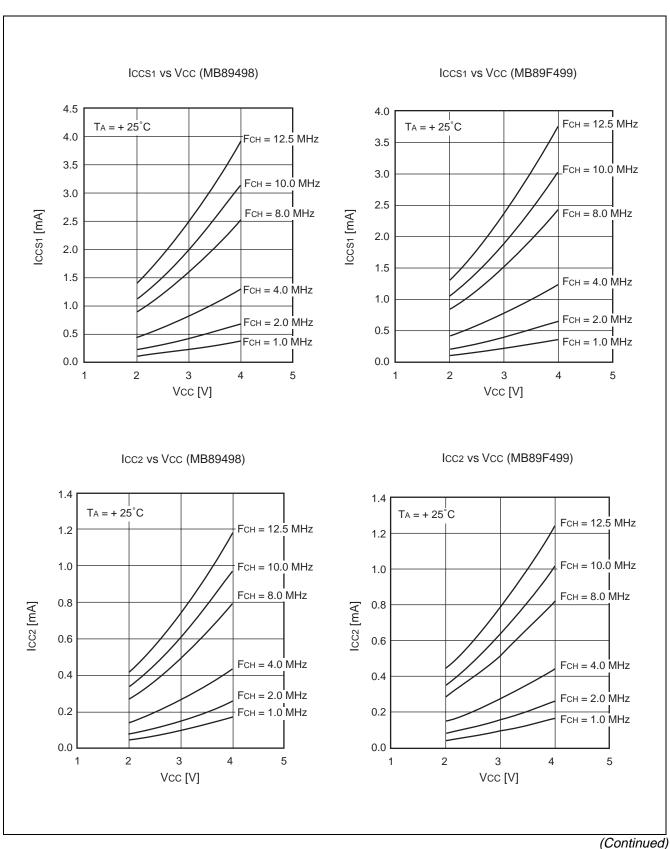


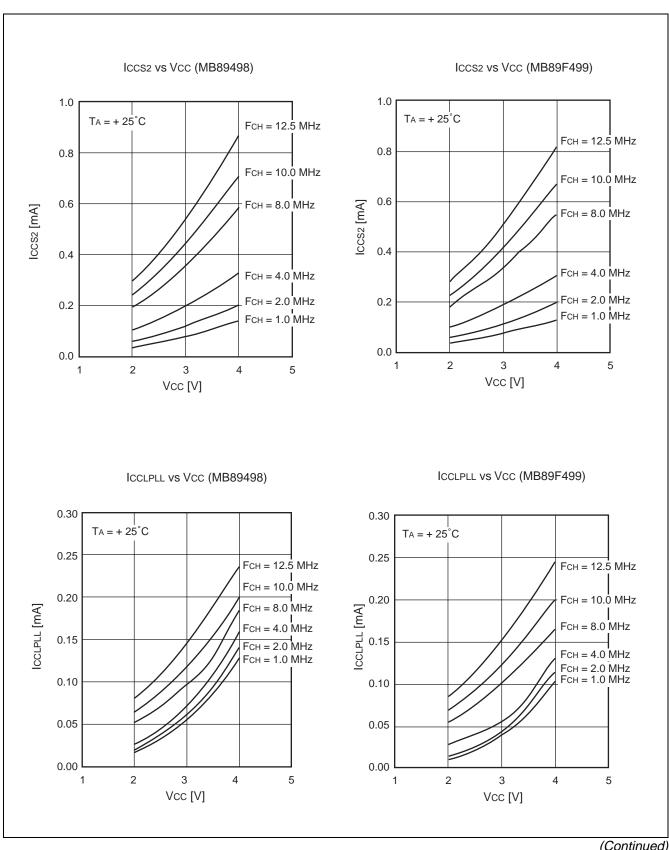




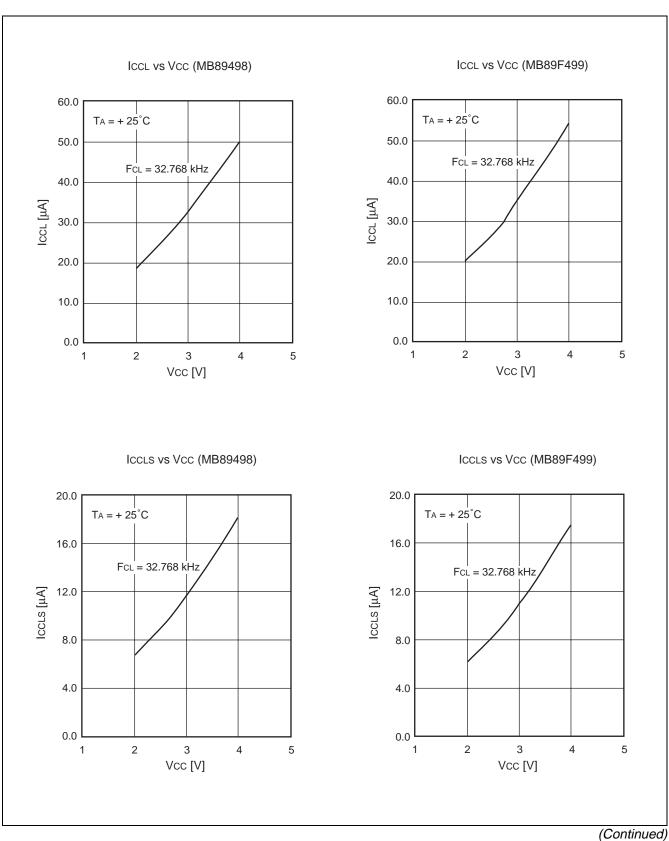




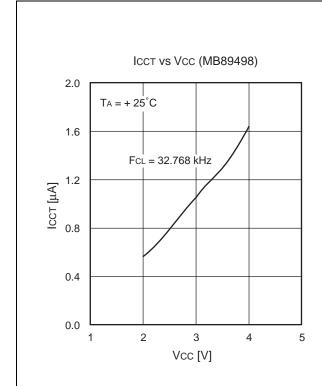


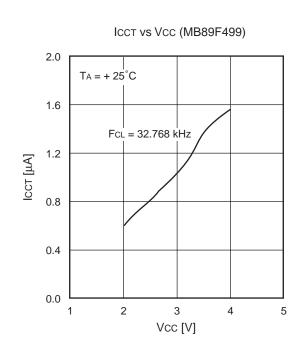


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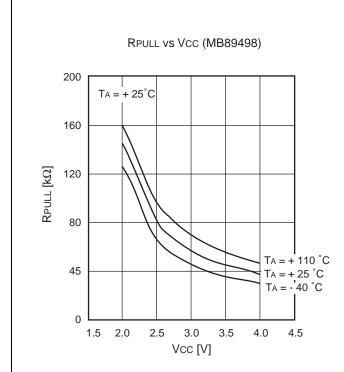


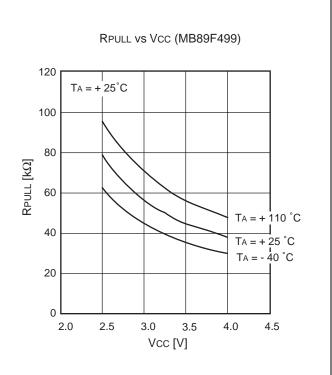






(4) Pull-up resistance





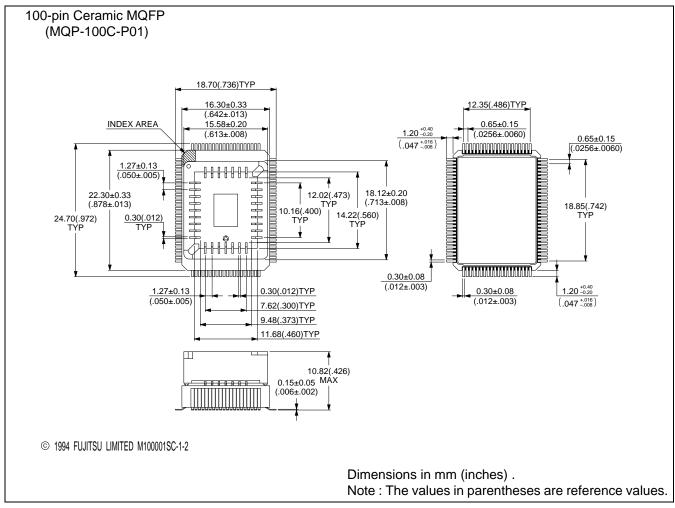
■ MASK OPTIONS

Part number	MB89498	MB89F499	MB89PV490
Specifying procedure	Specify when ordering mask	Setting no	t possible
Main clock oscillation stabilizationtime selection 2 ¹⁰ /Fcн 2 ¹⁴ /Fcн 2 ¹⁸ /Fcн	Selectable	Fixed to oscillation time of 2 ¹⁸ /FcH	n stabilization wait

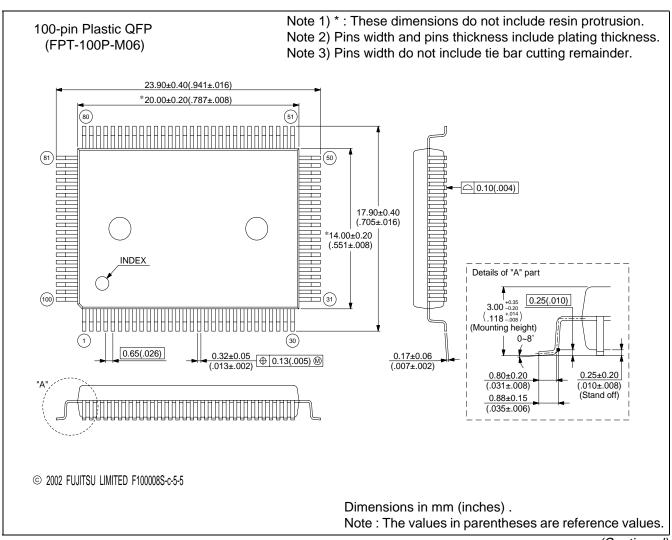
■ ORDERING INFORMATION

Part number	Package	Remarks
MB89498PF MB89F499PF	100-pin Plastic QFP (FPT-100P-M06)	
MB89498PFV MB89F499PFV	100-pin Plastic LQFP (FPT-100P-M05)	
MB89PV490CF	100-pin Ceramic MQFP (MQP-100C-P01)	

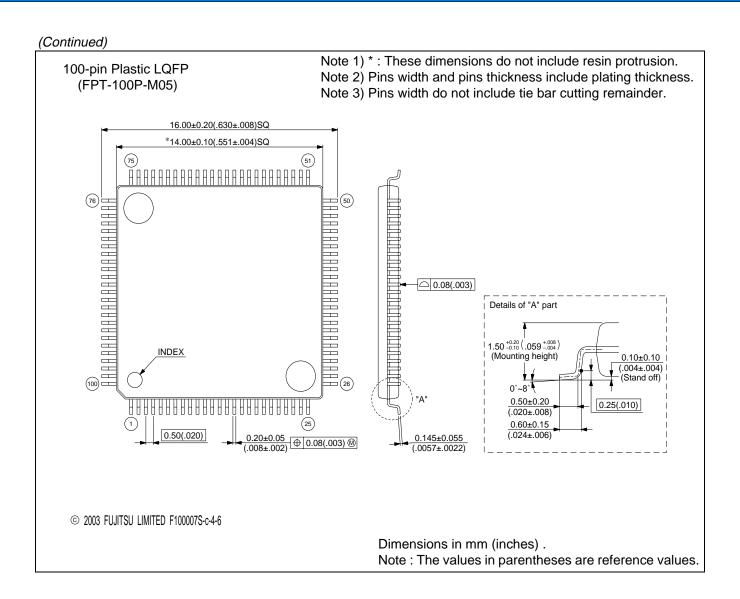
■ PACKAGE DIMENSIONS



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